SOT684-29(D)

HVQFN56, thermal enhanced very thin quad flat package, no leads, 56 terminals, 0.1 mm dimble wettable flank, 0.5 mm pitch, 8 mm x 8 mm x 0.9 mm body

29 November 2021 **Package information**

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN56
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	19-03-2021
Manufacturer package code	98ASA01750D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	7.9	8	8.1	mm
package width	7.9	8	8.1	mm
package height	0.8	0.9	1	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	56	-	

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2 Package outline

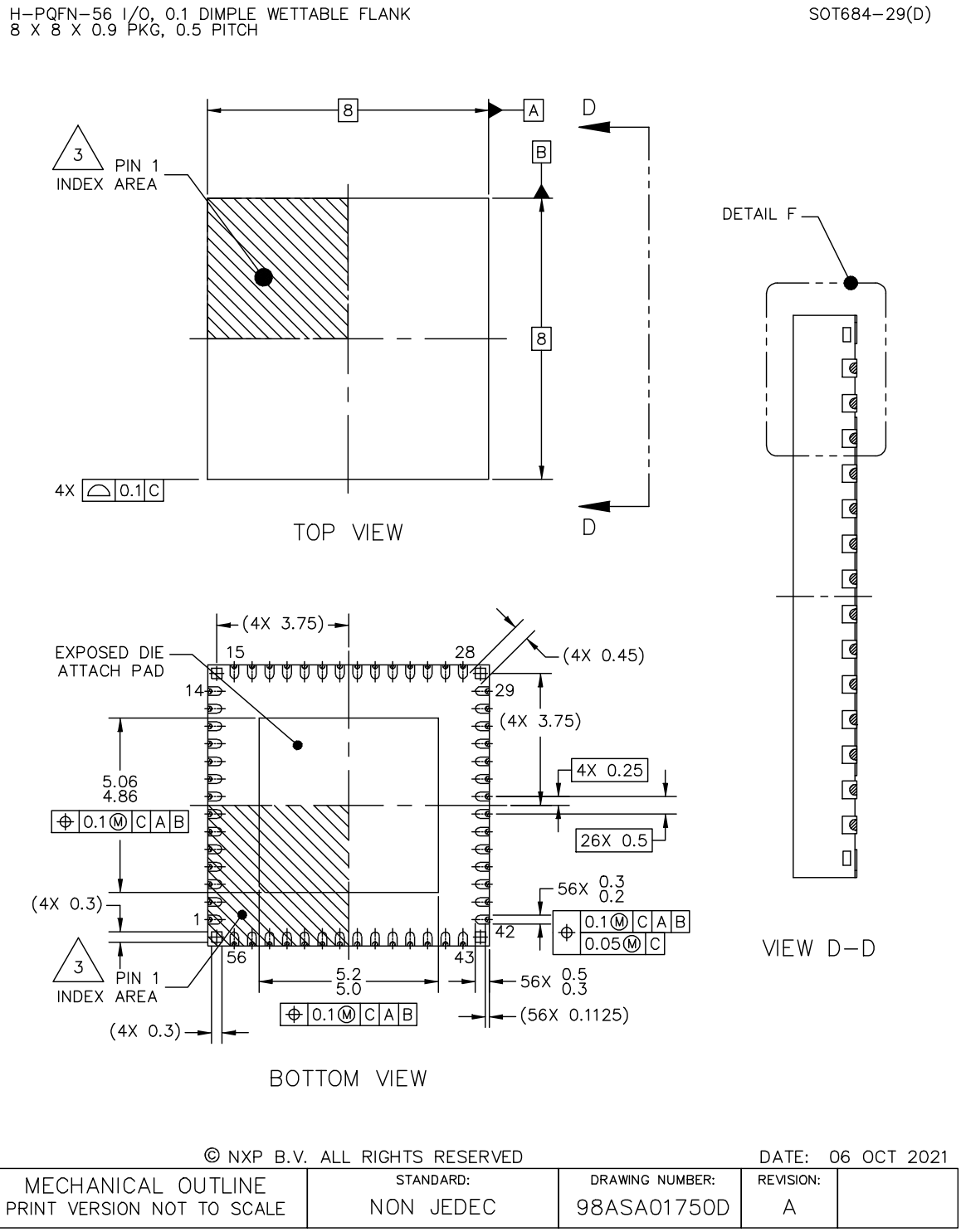
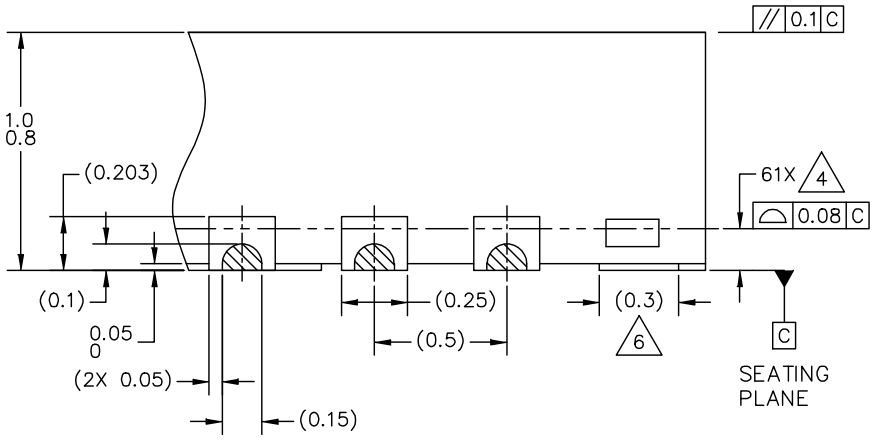


Figure 1. Package outline HVQFN56 (SOT684-29(D))

HVQFN56, thermal enhanced very thin quad flat package, no leads, 56 terminals, 0.1 mm dimble wettable flank, 0.5 mm pitch, 8 mm x 8 mm x 0.9 mm body

H–PQFN–56 I/O, 0.1 DIMPLE WETTABLE FLANK
8 X 8 X 0.9 PKG, 0.5 PITCH

SOT684–29(D)



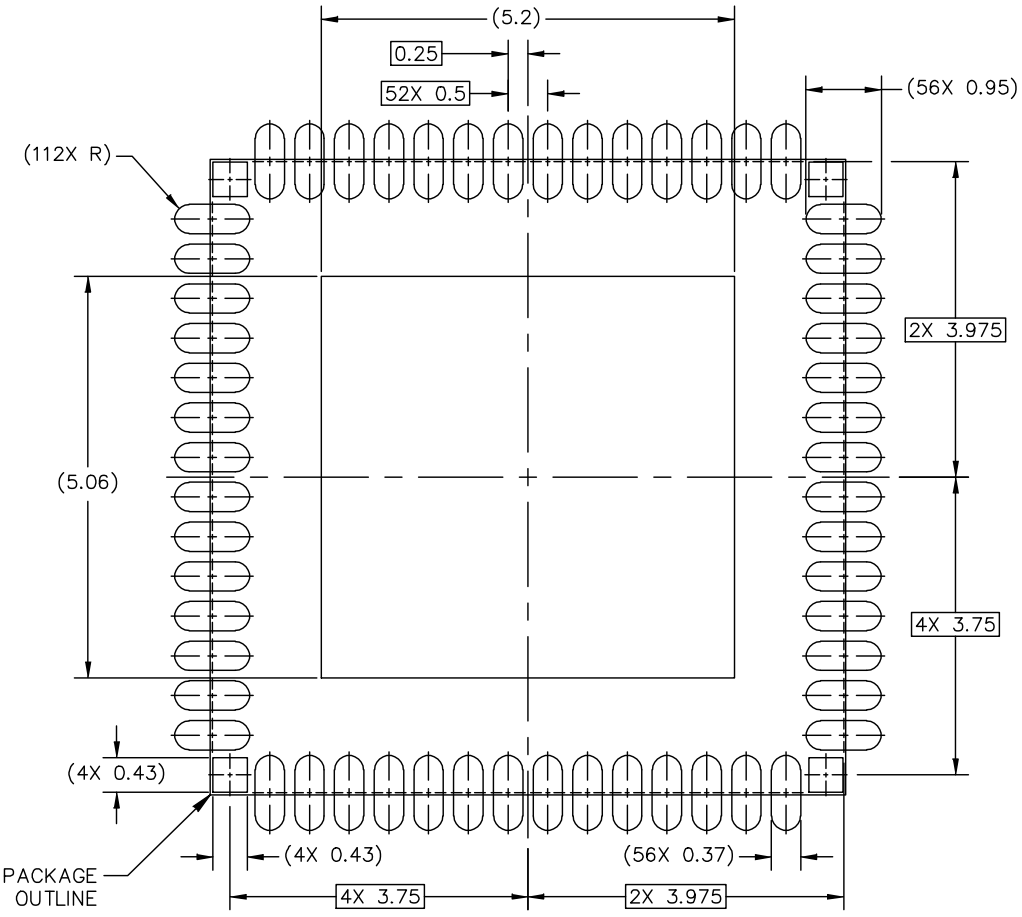
DETAIL F
VIEW ROTATED 90° CW

DATE: 06 OCT 2021

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01750D	REVISION: A	

Figure 2. Package outline detail of HVQFN56 (SOT684-29(D))

3 Soldering



PCB DESIGN GUIDELINES – SOLDER MASK OPENING PATTERN

THIS SHEET SERVES ONLY AS A GUIDELINE TO HELP DEVELOP A USER SPECIFIC SOLUTION. DEVELOPMENT EFFORT WILL STILL BE REQUIRED BY END USERS TO OPTIMIZE PCB MOUNTING PROCESSES AND BOARD DESIGN IN ORDER TO MEET INDIVIDUAL/SPECIFIC REQUIREMENTS.

DATE: 06 OCT 2021

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01750D	REVISION: A	

Figure 3. Reflow soldering footprint part1 for HVQFN56 (SOT684-29(D))

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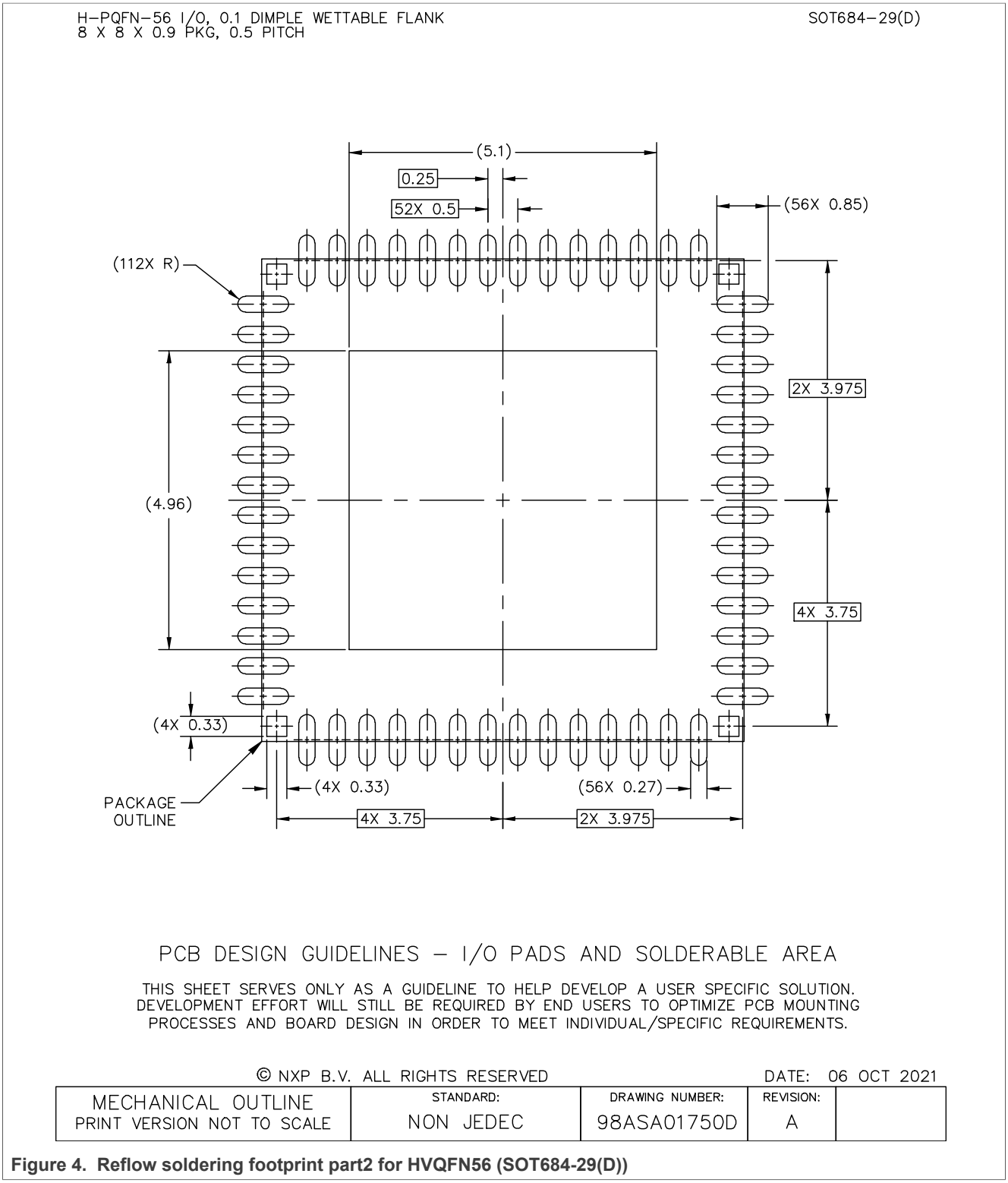

Figure 4. Reflow soldering footprint part2 for HVQFN56 (SOT684-29(D))

HVQFN56, thermal enhanced very thin quad flat package, no leads, 56 terminals, 0.1 mm dimble wettable flank, 0.5 mm pitch, 8 mm x 8 mm x 0.9 mm body

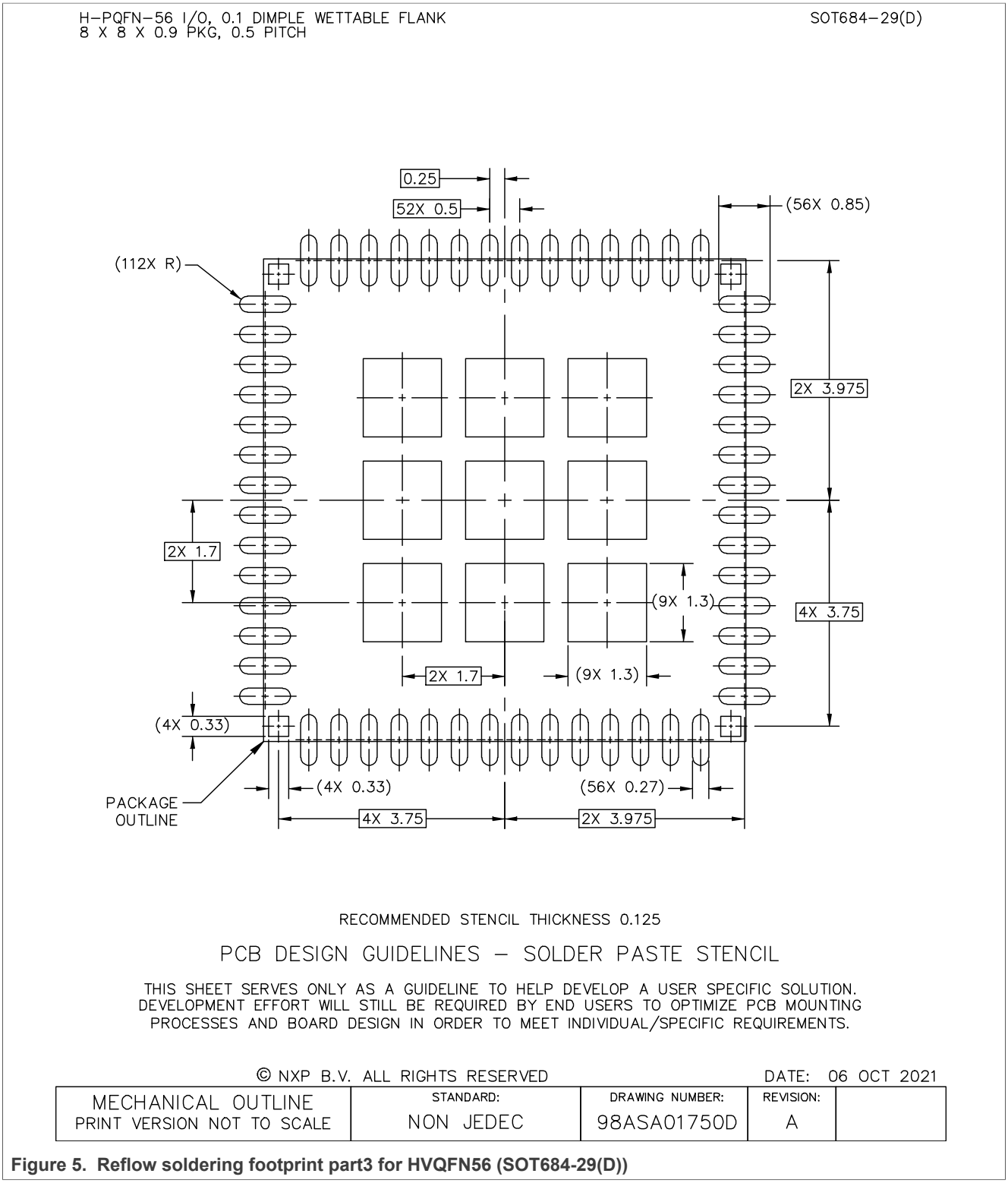

Figure 5. Reflow soldering footprint part3 for HVQFN56 (SOT684-29(D))

HVQFN56, thermal enhanced very thin quad flat package, no leads, 56 terminals, 0.1 mm dimble wettable flank, 0.5 mm pitch, 8 mm x 8 mm x 0.9 mm body

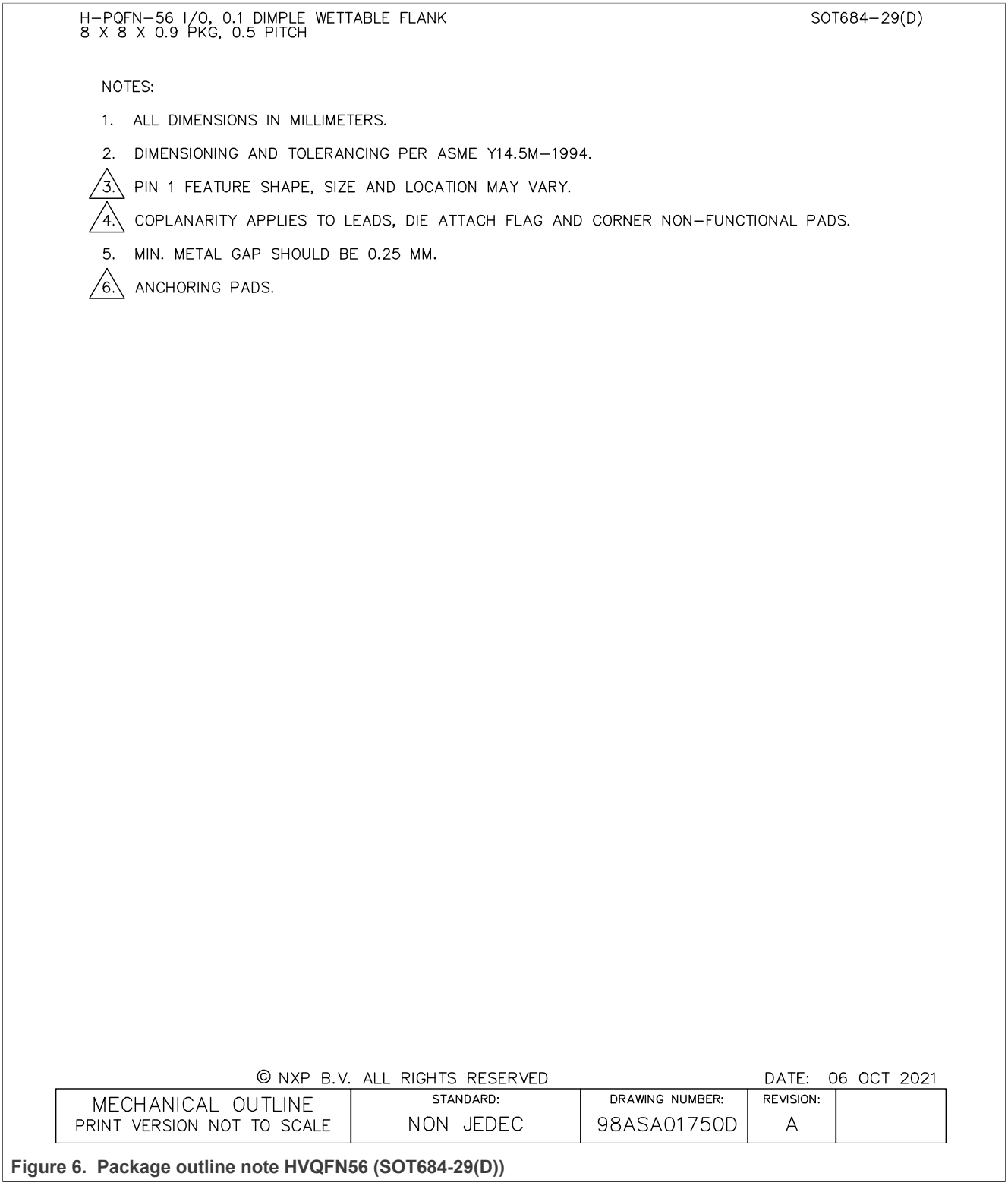

Figure 6. Package outline note HVQFN56 (SOT684-29(D))

4 Legal information

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For more information, please visit: http://www.nxp.com
For sales office addresses, please send an email to: salesaddresses@nxp.com

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